

■ FEATURES

- Extremely compact ceramic(alumina) substrate
- Precision screened thick film resistors
- Ratio matching and functional trimming
- Surface mounted active and passive components
- Chip and wire capability
- Flexible lead configuration
- Conformal epoxy coating

■ CONSTRUCTION

- Substrate-96% alumina
- Resistors -thick film, laser trimmed
- Conductors multilayered thick film
- Insulators-thick film glass
- Leaded packages-SIP,DIP,SOP
- Leadless packages-as specified by customer

